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Modified 9-98

PTO/SB/21 (12-97)

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Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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TRANSMITTAL FORM

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BOX: NON-FEE AMENDMENT

Express Mail
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Application / Conf. No.

09/879,875 / 4969

Filing Date

June 11, 2001

First Named Inventor

Abu K. Eghan

Examiner Name

Evan T. Pert

Group Art Unit

2829

Issue Fee Batch No.

Attorney Docket Number

X-901 US

ENCLOSURES (check all that apply)

☐ Fee Transmittal Form☒ Amendment / Response☐ Preliminary Amendment☐ After Final☐ Affidavit(s)/declaration(s)☐ Extension of Time Request☐ Change Status to LARGE ENTITY☐ Express Abandonment Request☐ Information Disclosure Statement☐ Substitute PTO-1449(s)
IDS by Applicant (PTO/SB/08A)☐ Certified Copy of Priority
Document(s)☐ Response to Missing Parts/
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X-901 US
09/879,875

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abu K. Eghan et al.

Assignee: Xilinx, Inc.

Title: High Performance Flipchip Package That
Incorporates Heat Removal With Minimal
Thermal Mismatch

Serial No.: 09/879,875 File Date: 6/11/01

Examiner: Evan T. Pert Art Unit: 2829

Docket No.: X-901 US

BOX NON-FEE AMENDMENT
COMMISSIONER FOR PATENTS
Washington, D.C. 20231

AMENDMENT IN RESPONSE TO THE SECOND OFFICE ACTION

Dear Sir:

In response to the Second Office Action mailed from the Patent Office July 26, 2002, please replace and add the new claims as indicated. In addition, please replace a paragraph in the specification as indicated.

In the Specification

Please replace paragraph [0016] with the following:

[0016] Also, as a feature of the invention, because the cavity wall is part of the continuous substrate, it is possible to extend some circuit function into the wall. In particular, plate capacitors in the wall can serve as high frequency bypass capacitors in proximity to the die. The wall of the single unitary structure may include interleaved conductive layers forming one or more chip capacitors for high frequency bypass purposes. When the single unitary structure is formed primarily of material with moderate dielectric constant (and CTE of 5 to 9 ppm/°C) such as ceramic or glass material, conductive and insulating materials may be formed in successive thin layers to create

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